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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/777,922	02/07/2001	Ikuo Kohashi	925-175	6185
75	590 09/02/2003	•		
NIXON & VANDERHYE P.C. 1100 North Glebe Road, 8th Floor Arlington, VA 22201-4714			EXAMINER	
			RODRIGUEZ, ARMANDO	
		•	ART UNIT	PAPER NUMBER
			2828	
			DATE MAILED: 09/02/2003	

Please find below and/or attached an Office communication concerning this application or proceeding.

Applicati n N . Office Action Summary Examiner Armando Rodriguez Th MAILING DATE of this communication appears n the cover sh et with the correspondence address Period for Reply A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM					
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Period for Reply					
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM					
THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely. - If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication. - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). - Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b). Status					
1) Responsive to communication(s) filed on 10 June 2003.					
2a) This action is FINAL . 2b) ☑ This action is non-final.					
3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims					
4)⊠ Claim(s) <u>1-3 and 11-16</u> is/are pending in the application.					
4a) Of the above claim(s) is/are withdrawn from consideration.					
5) Claim(s) is/are allowed.					
5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) <u>1-3 and 11-16</u> is/are rejected. 7) ☐ Claim(s) is/are objected to PAUL IP					
SUPERVISORY PATENT EXAMINER					
8) Claim(s) are subject to restriction and/or election requirement. TECHNOLOGY CENTER 2800 Application Papers					
9) The specification is objected to by the Examiner.					
10) ☐ The drawing(s) filed on is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.					
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).					
11) The proposed drawing correction filed on is: a) approved b) disapproved by the Examiner.					
If approved, corrected drawings are required in reply to this Office action.					
12)☐ The oath or declaration is objected to by the Examiner.					
Priority under 35 U.S.C. §§ 119 and 120					
13) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).					
a)⊠ All b)□ Some * c)□ None of:					
1. Certified copies of the priority documents have been received.					
2. Certified copies of the priority documents have been received in Application No					
 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 					
14) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).					
 a) ☐ The translation of the foreign language provisional application has been received. 15)☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121. 					
Attachment(s)					
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449) Paper No(s)					

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Response to Arguments

Applicant's arguments with respect to claims 1-3 and 11-16 have been considered but are moot in view of the new ground(s) of rejection.

However, applicant's amendment regarding 35 USC 112 rejection of claims 1,13 and 14 does not overcome the rejection, because there is no structure recited to obtain a semiconductor laser apparatus but only a method of die-bonding a laser chip.

Regarding claim 14, the claim recites an intended use.

Priority

English translation for the foreign priority document Japanese Patent Application 2000-028554 filed on February 7, 2000 has been acknowledge, which overcomes the cited prior art reference of Kohashi et al (US 2001/0002916) thereby the rejection has been withdrawn.

Claim Rejections - 35 USC § 112

The following is a quotation of the second paragraph of 35 U.S.C. 112:

The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.

Claims 1-3,11-16 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

Claims 1,13 and 14 pertain to a semiconductor laser apparatus, however applicant has failed to recite any structural elements for obtaining a semiconductor laser apparatus but only recites a process of die-bonding a semiconductor laser chip to a surface.

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Regarding claim 14,

The preamble recites an intended use of a semiconductor laser apparatus in an optical pickup.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1-3 and 11-16 are rejected under 35 U.S.C. 103(a) as being unpatentable over Tsuji Akira (JP11284098) in view of Honda et al (PN 6,210,811).

Regarding claims 1-3,13 and 14

Tsuji Akira discloses a laser chip (1) die-bonded to a surface (2) using a brazing material (3), as shown in figure 6(b). The detailed description discloses the brazing having a vertical length of 10 *u*m or more, but does not interrupt laser emission.

Tsuji Akira does not disclose using an epoxy resin as the die-bonding material. However, epoxy resin, solder or brazing are among some of the well-known die bonding techniques. Honda et al discloses in column 1 line 22, the use of epoxy resin for use as die bonding in semiconductor packages. Column 5 discloses the epoxy resin having a composition, which includes conductive particles such as silver.

Therefore, it would have obvious to a person having ordinary skill in the art at the

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time the invention was made to use the epoxy resin of Honda et al to die-bond the laser

chip of Tsuji Akira to a surface because it would provide a conductive die-bonding

material.

Regarding claims 12 and 13,

Claims 12 and 13 recite the particulars of a percentage of the metal particles

within the epoxy resin, it would have been obvious to a person having ordinary skill in

the art at the time the invention was made to obtain these working ranges, since the

general conditions of the claim are disclosed in the cited prior art of Honda et al,

obtaining the optimum working ranges involves only routine skill in the art.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Armando Rodriguez whose telephone number is (703) 308-6218. The

examiner can normally be reached on 10-hour day / M-F.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's

supervisor, Paul Ip can be reached on (703) 308-3098. The fax phone number for the

organization where this application or proceeding is assigned is (703) 872-9306.

Any inquiry of a general nature or relating to the status of this application or proceeding

should be directed to the receptionist whose telephone number is (703) 308-4881.

Armando Rødriguez

Examiner

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Paul Ip

Supervisor

Art Unit 2828

AR/PI